DW OR N PACKAGE

(TOP VIEW)

SLAS063B - APRIL 1989 - REVISED MARCH 2007

- Easy Microprocessor Interface
- On-Chip Data Latches
- Digital Inputs Are TTL-Compatible With 10.8-V to 15.75-V Power Supply
- Monotonic Over the Entire A/D Conversion Range
- Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPE	CIFICATIONS
Resolution	8 bits
Linearity Error	1/2 LSB
Power Dissipation	20 mW
Settling Time	100 ns
Propagation Delay Time	80 ns

20 OUTB AGND [OUTA] 2 19 ∏ RFBB 18 REFB RFBA [REFA [17 V_{DD} 16 WR DGND ∏ 5 DACA/DACB 6 15 T CS 14 DB0 (LSB) (MSB) DB7 [DB6 **∏** 8 13 DB1 12 DB2 DB5 **1** 9 DB4 [11 DB3

description

The TLC7628C is a dual, 8-bit, digital-to-analog converter (DAC) designed with separate on-chip data latches and featuring exceptionally close DAC-to-DAC matching. Data are transferred to either of the two DAC data latches through a common, 8-bit input port. Control input DACA/DACB determines which DAC is loaded. The load cycle of this device is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

The TLC7628C operates from a 10.8-V to 15.75-V power supply and is TTL-compatible over this range. 2- or 4-quadrant multiplying makes this device a sound choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7628C is characterized for operation from 0°C to +70°C.

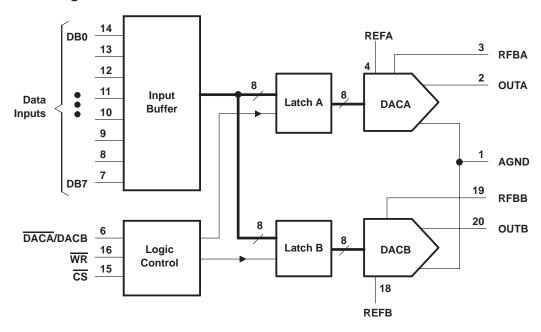


Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

All trademarks are the property of their respective owners.



functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{DD} (to AGND or DGND)	–0.3 V to 17 V
Voltage between AGND and DGND	V _{DD}
Input voltage range, V _I (to DGND)	–0.3 V to $V_{\mbox{\scriptsize DD}}$ + 0.3 V
Reference voltage range, V _{refA} or V _{refB} (to AGND)	±25 V
Feedback voltage range, V _{RFBA} or V _{RFBB} (to AGND)	±25 V
Output voltage range, V _{OA} or V _{OB} (to AGND)	±25 V
Peak input current	10 μΑ
Operating free-air temperature range, T _A : TLC7628C	0°C to +70°C
Storage temperature range, T _{stq}	65°C to +150°C
Case temperature for 10 seconds, T _C : FN package	+260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	+260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.



recommended operating conditions

		IIM	NOM	MAX	UNIT
Supply voltage, V _{DD}		10.	3	15.75	V
Reference voltage, V _{refA} or V _{refB}			±10		V
High-level input voltage, VIH		2.	1		V
Low-level input voltage, V _{IL}				8.0	V
CS setup time, t _{Su(CS)}		5)		ns
CS hold time, th(CS) (see Figure 1))		ns
DAC select setup time, t _{su(DAC)} (see Figure 1)		6)		ns
DAC select hold time, t _{h(DAC)} (see Figure 1)		1)		ns
Data bus input setup time $t_{SU(D)}$ (see Figure	1)	2:	5		ns
Data bus input hold time th(D) (see Figure 1)		1)		ns
Pulse duration, WR low, t _{W(WR)} (see Figure 1)		5)	_	ns
Operating free-air temperature, TA	TLC7628C)	+70	°C

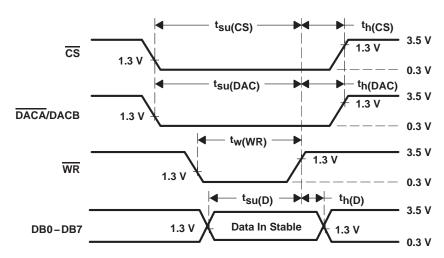
electrical characteristics over recommended ranges of operating free-air temperature and V_{DD} , $V_{refA} = V_{refB} = 10 \text{ V}$, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

	PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT	
				Full range		10		
ΙΗ	High-level input current		$V_I = V_{DD}$	25°C		1	μΑ	
L	Law law Canada assessed		V. 0	Full range		-10		
^I IL	Low-level input current		V _I = 0	25°C		-1	μΑ	
	Reference input impedance RE AGND	FA or REFB to			5	20	kΩ	
		CUTA	DAC data latch loaded with 00000000,	Full range		±200		
1.	Output lealings aumont	OUTA	$V_{refA} = \pm 10 \text{ V}$	25°C		±50	nA	
l _{kg}	Output leakage current	OUTB	DAC data latch loaded with 00000000,	Full range		±200		
		OOTB	$V_{refB} = \pm 10 \text{ V}$	25°C		±50		
	Input resistance match (REFA to	REFB)				±1%		
	DC aventus associativitas Ameira(A)(-	_	AV/ 1.5.0/	Full range		0.02	07/07	
	DC supply sensitivity Δgain/ΔV _E	DD .	$\Delta V_{DD} = \pm 5 \%$			0.01	%/%	
		Quiescent	All digital inputs at V _{IH} min or V _{IL} max			2		
I_{DD}	Supply current	Cton dh	All distinctions to at 0 V as V	Full range		0.5	mA	
		Standby	All digital inputs at 0 V or V _{DD}	25°C		0.1	<u> </u>	
		DB0-DB7				10		
Ci	Input capacitance WR, CS, DACA/DACB					15	pF	
C	Output conscitones (OUTA OUTD)		DAC data latches loaded with 00000000			25	pF	
co	Output capacitance (OUTA, OU	10)	DAC data latches loaded with 11111111			60		

operating characteristics over recommended ranges of operating free-air temperature and V_{DD} , $V_{refA} = V_{refB} = 10 \text{ V}$, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER			TEST CONDITIONS	MIN TYP MAX			UNIT
Linearity error						±1/2	LSB
Settling time (to 1/2 L	_SB)	See Note 1				100	ns
		Full range				±3	1.00
Gain error		See Note 2	25°C			±2	LSB
407 111 1	REFA to OUTA	0 11 1 0	Full range			-65	ID.
AC feedthrough	REFB to OUTB	See Note 3	25°C			-75	dB
Temperature coefficient of gain						±0.0035	%FSR/°C
Propagation delay (fr 90% of final analog of	• •	See Note 4				80	ns
Channel-to-channel	REFA to OUTB	See Note 5	25°C		80		i.D.
isolation	REFB to OUTA	See Note 6	25°C		80		dB
Digital-to-analog glitch impulse area		Measured for cod T _A = 25°C	de transition from 00000000 to 11111111,		330		nV∙s
Digital crosstalk		Measured for cod T _A = 25°C	de transition from 00000000 to 111111111,		60		nV∙s
Harmonic distortion		$V_i = 6 \text{ V}, \text{ f} = 1 \text{ kH}$	Hz, T _A = 25°C		-85		dB

- NOTES: 1. OUTA, OUTB load = 100Ω , $C_{ext} = 13 pF$; \overline{WR} and \overline{CS} at 0 V; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
 - 2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) = V_{ref} 1 LSB. Both DAC latches are loaded with 11111111.
 - 3. V_{ref} = 20 V peak-to-peak, 10-kHz sine wave
 - 4. $V_{refA} = V_{refB} = 10 \text{ V}$; OUTA/OUTB load = 100 Ω , $C_{ext} = 13 \text{ pF}$; \overline{WR} and \overline{CS} at 0 V; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
 - 5. $V_{refA} = 20 \text{ V peak-to-peak}$, 10-kHz sine wave; $V_{refB} = 0$
 - 6. V_{refB} = 20 V peak-to-peak, 10-kHz sine wave; V_{refA} = 0



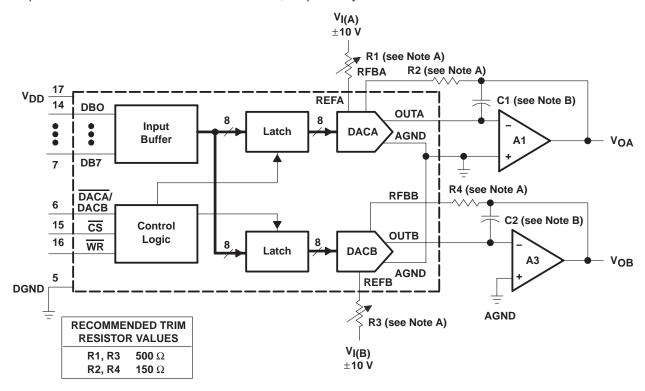
For all input signals, $t_r = t_f = 5$ ns (10% to 90% points).

Figure 1. Setup and Hold Times



APPLICATION INFORMATION

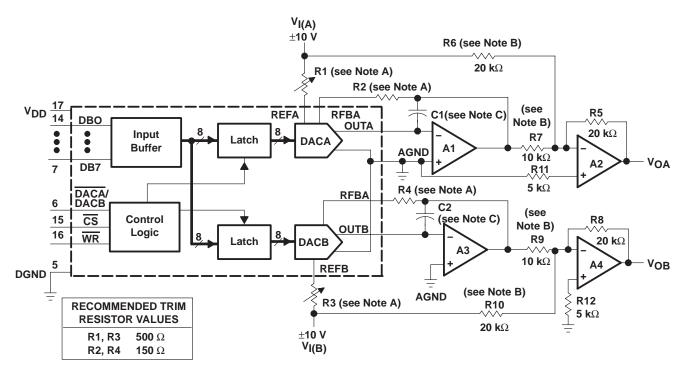
This device is capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figures 2 and 3. Input coding for unipolar and bipolar operation are summarized in Tables 2 and 3, respectively.



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
 - B. C1 and C2 phase compensation capacitors (10 pF to 15 pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

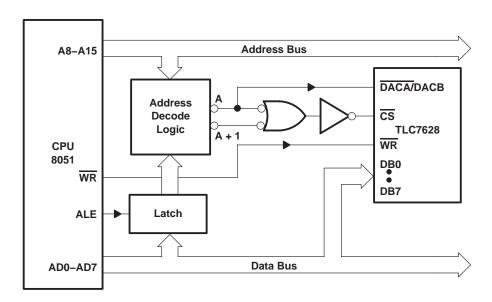
Figure 2. Unipolar Operation (2-Quadrant Multiplication)

APPLICATION INFORMATION



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Adjust R1 for V_{OA} = 0 V with code 10000000 in DACA latch. Adjust R3 for V_{OB} = 0 V with 10000000 in DACB latch.
 - B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
 - C. C1 and C2 phase compensation capacitors (10 pF to 15 pF) may be required if A1 and A3 are high-speed amplifiers.

Figure 3. Bipolar Operation (4-Quadrant Operation)

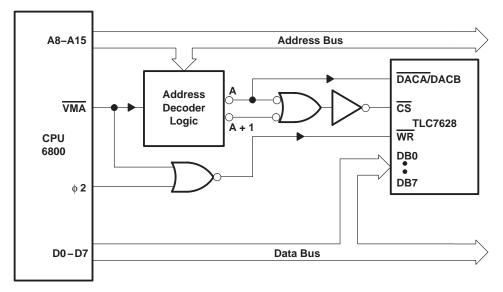


NOTE D: A = decoded address for TLC7628 DACA A + 1 = decoded address for TLC7628 DACB

Figure 4. TLC7628 — Intel 8051 Interface



APPLICATION INFORMATION



NOTE D: A = decoded address for TLC7628 DACA A + 1 = decoded address for TLC7628 DACB

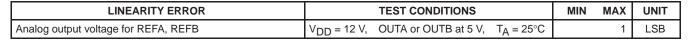
Figure 5. TLC7628 - 6800 Interface

voltage-mode operation

The current-multiplying DAC in the TLC7628C can be operated in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. An example of a current-multiplying DAC operating in voltage mode is shown in Figure 6. The relationship between the fixed input voltage and the analog output voltage is given by the following equation:

Analog output voltage = fixed input voltage (D/256)

where D = the digital input. In voltage-mode operation, these devices meet the following specification:



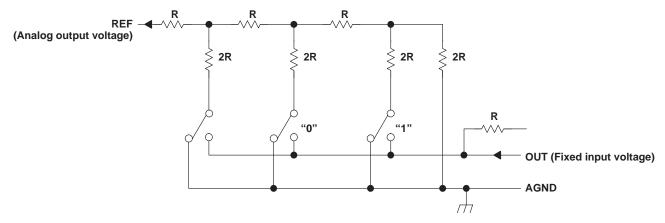


Figure 6. Current-Multiplying DAC Operating in Voltage Mode



PRINCIPLES OF OPERATION

This device contains two, identical, 8-bit, multiplying DACs: DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between the DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified D/A circuit for DACA or DACB with all digital inputs low is shown in Figure 7.

Figure 8 shows the DACA or DACB equivalent circuit. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the reference current flows to OUTA. A small leakage current (I_{lkg}) flows across internal junctions, and as with most semiconductor devices, doubles every 10°C. The C_0 is caused by the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of C_0 is 25 pF to 60 pF maximum. The equivalent output resistance (I_0) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

The TLC7628C interfaces to a microprocessor through the data bus, $\overline{\text{CS}}$, $\overline{\text{WR}}$, and $\overline{\text{DACA/DACB}}$ control signals. When $\overline{\text{CS}}$ and $\overline{\text{WR}}$ are both low, the analog output on this device, specified by the $\overline{\text{DACA/DACB}}$ control line, responds to the activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the $\overline{\text{CS}}$ signal or $\overline{\text{WR}}$ signal goes high, the data on the DB0–DB7 inputs are latched until the $\overline{\text{CS}}$ and $\overline{\text{WR}}$ signals go low again. When $\overline{\text{CS}}$ is high, the data inputs are disabled, regardless of the state of the $\overline{\text{WR}}$ signal.

The digital inputs of the TLC7628C provides TTL compatibility when operated from a supply voltage of 10.8 V to 15.75 V.

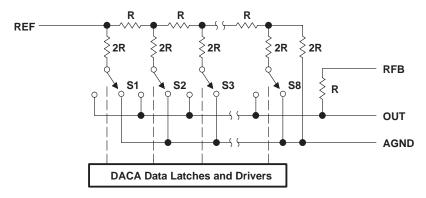


Figure 7. Simplified Functional Circuit for DACA or DACB

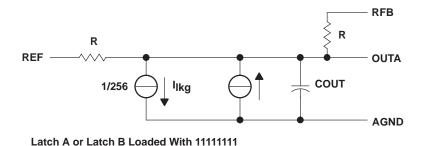


Figure 8. TLC7628 Equivalent Circuit for DACA or DACB



PRINCIPLES OF OPERATION

Table 1. Mode Selection Table

DACA/DACB	CS	WR	DACA	DACB
L	L	L	Write	Hold
Н	L	L	Hold	Write
X	Н	Х	Hold	Hold
X	Х	Н	Hold	Hold

L = low level, H = high level, X = don't care

Table 2. Unipolar Binary Code

DAC LATCH CONTENTS (see Note 7)	ANALOG OUTPUT
MSB LSB	ANALOG GOTFOT
1111111 10000001 10000000 01111111 000000	-V _I (255/256) -V _I (129/256) -V _I (128/256) = -V _I /2 -V _I (127/256) -V _I (1/256)
0000000	$-V_{I}(0/256) = 0$

Table 3. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS (see Note 8)	ANALOG OUTPUT
MSB LSB	
1111111	V _I (127/128)
1000001	V _I (1/128)
1000000	0 V
0111111	−V _I (1/128)
0000001	-V _I (127/128)
0000000	-V _I (128/128)

NOTES: 7. $1 LSB = (2^{-8})V_{\parallel}$ 8. $1 LSB = (2^{-7})V_{\parallel}$





UMENTS
v.ti.com 2-Feb-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
TLC7628CDW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7628CDWG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7628CDWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7628CDWRG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
TLC7628CN	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7628CNE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
TLC7628IN	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Applications Products Amplifiers amplifier.ti.com Audio www.ti.com/audio Data Converters Automotive www.ti.com/automotive dataconverter.ti.com DLP® Products Broadband www.dlp.com www.ti.com/broadband DSP Digital Control dsp.ti.com www.ti.com/digitalcontrol Clocks and Timers www.ti.com/clocks Medical www.ti.com/medical Military Interface www.ti.com/military interface.ti.com Optical Networking Logic logic.ti.com www.ti.com/opticalnetwork Power Mgmt power.ti.com Security www.ti.com/security Telephony Microcontrollers microcontroller.ti.com www.ti.com/telephony Video & Imaging www.ti-rfid.com www.ti.com/video RF/IF and ZigBee® Solutions www.ti.com/lprf Wireless www.ti.com/wireless

> Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2009, Texas Instruments Incorporated